

ENGINEERING	PRODUCT SPECIFICATION	SPEC.NO.:	SPCP046A
DEPT.	For CP05 Series Halogen-Free Power Connector	PAGE:	1/4

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment

MIL - STD - 1344 Test methods for electrical connectors

J-STD-020 Resistance to soldering Temperature for through hole Mounted Devices SS-00254 Test methods for electronic components ,LEAD-FREE soldering Part design

standards

3. APPLICABLE SERIES NO.: Housing: CP0502S0000 (Halogen-Free)

Header: CP0502P*M*0-NH (Halogen-Free) CP0502P*H*0-NH (Halogen-Free)

Terminal: CP05T021PE0

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 P.C. Board Layout: See attached drawings



REVIEWED : Alex APPROVED : Eisley VERIFIED : Eager .



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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.0A (AWG #24) , 1400V AC/DC
7.2	Contact resistance	Dry circuit of DC 20mV max., 100mA max., Wire resistance shell be removed from the measured value.	Less than 10 mΩ
7.3	Dielectric strength	When applied AC 3800 V 1 minute between adjacent terminal	No Breakdown
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than $1000 \text{ M}\Omega$

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIR	REMENT	
8.1	Wire size	Specified wire size	Accepts AWG#24-#28		
8.2	Terminal crimp	When crimped AWG#24 size wire	More than 3	3 kgf.	
	strength	When crimped AWG#26 size wire	More than 2 kgf		
		When crimped AWG#28 size wire	More than	1.3 kgf	
8.3	Terminal insertion force	Insertion speed 25± 3 mm per minute into housing	Less than 0	.5 Kgf	
8.4	Terminal retaining force in insulator	Retention speed 25± 3 mm per minute from Wire to Wire Housing	More than 1.0 kgf		
8.5	Single contact insertion force	Measure force to insertion using mating square pin at speed 25± 3 mm per minute	500 gram max.		
8.6	Single contact withdrawal force	Measure force to withdrawal using mating square pin at speed 25± 3 mm per minute	100 gram min.		
8.7	Pin retention force in Board mount Header	Push Pin from insulator base at speed 25± 3 mm per minute	More than ().7 kgf	
8.8	Mating and Unmating force	Speed 25± 3 mm per minute	Mating Unmating (Max.) (Min.)		
			2.5 kgf	0.5 kgf	
8.9	Durability	· · · · · · · · · · · · · · · · · · ·		Contact resistance:	
	insertion and withdrawal		Less than twice of initial		



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9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ/minute each 2 hours for X, Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Heat aging	85± 2°C, 96 hours	No damage
9.4	Humidity	40± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.5	Temperature cycling	One cycle consists of: (1) -55 ⁺⁰ ₋₃ °C, 30 min. (2) Room temp. 10-15 min. (3) 85 - 0 °C, 30 min. (4) Room temp. 10-15 min. Total cycle: 5 cycle	Appearance: No damage Contact resistance: Less than twice of initial
9.6	Salt spray	Temperature: 35± 3°C Solution: 5± 1% Spray time: 48± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial
9.7	Solder ability	Tin-Lead Process Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5°C Lead-Free Process Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area



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	ITEM	TEST CONDITION	REQUIREMENT
9.8	Resistance to	DIP Type Lead-Free Process:	No damage
	soldering heat	Soldering time: 5 ± 0.5 second	
		Soldering pot: 260 ± 5°C	
		SMT Type Lead-Free Process:	
		Soldering time: 20 second Max.	
		Soldering pot: 250~260°C	
		Refer Reflow temperature profile(11.2)	

10. AMBIENT TEMPERATURE RANGE: -25 to +85°

- 11. Recommended IR Reflow Temperature Profile:
- 11.1 Using Lead-Free Solder Paste

